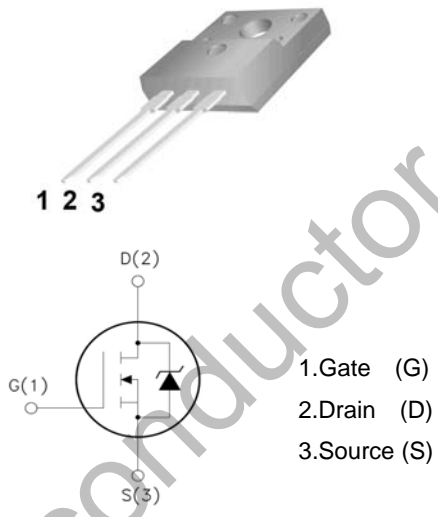


WGF9N90S

Features:

- Low Intrinsic Capacitances.
- Excellent Switching Characteristics.
- Extended Safe Operating Area.
- Unrivalled Gate Charge: Qg= 60nC (Typ.).
- VDSS=900V, ID=9A
- R_{DS(on)} : 1.0Ω (Max) @V_G=10V
- 100% Avalanche Tested

TO-220F



1. Gate (G)
2. Drain (D)
3. Source (S)

Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	900	V
I _D	Drain Current	T _C =25°C	9
		T _C =100°C	5.45
V _{GSS}	Gate - Source voltage	±30	V
E _{AS}	Single Pulse Avalanche Energy (note1)	410	mJ
I _{AR}	Avalanche Current (note2)	9	A
P _D	Power Dissipation (T _j =25°C)	50	W
T _j	Junction Temperature(MAX)	150	°C
T _{stg}	Storage Temperature	-55~+150	°C
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJC}	Thermal Resistance, Junction to Case	-	2.5	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient	-	65	°C/W

Electrical Characteristics (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0	900	-	-	V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =250μA, Reference to 25°C	-	0.9	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =900V, V _{GS} =0V	-	-	10	μA
		V _{DS} =720V, T _C =125°C	-	-	100	
I _{GSSF}	Gate-body leakage Current, Forward	V _{GS} =+30V, V _{DS} =0V	-	-	100	nA
I _{GSSR}	Gate-body leakage Current, Reverse	V _{GS} =-30V, V _{DS} =0V	-	-	-100	
On Characteristics						
V _{GS(TH)}	Gate Threshold Voltage	I _D =250μA, V _{DS} =V _{GS}	3	-	5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	I _D =4.5A, V _{GS} =10V	-	0.85	1.0	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0, f=1.0MHz	-	2630	-	pF
C _{oss}	Output Capacitance		-	190	-	
C _{rss}	Reverse Transfer Capacitance		-	18	-	
Switching Characteristics						
T _{d(on)}	Turn-On Delay Time	V _{DD} =450V, I _D =9A R _G =25Ω (Note 3,4)	-	64	110	ns
T _r	Turn-On Rise Time		-	105	250	
T _{d(off)}	Turn-Off Delay Time		-	155	210	
T _f	Turn-Off Rise Time		-	84	160	
Q _g	Total Gate Charge	V _{DS} =720, V _{GS} =10V, I _D =9A	-	60	-	nC
Q _{gs}	Gate-Source Charge		-	13	-	
Q _{gd}	Gate-Drain Charge		-	27	-	
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Max. Diode Forward Current	-	-	-	9	A
I _{SM}	Max. Pulsed Forward Current	-	-	-	36	
V _{SD}	Diode Forward Voltage	I _D =9A	-	-	1.4	V
T _{rr}	Reverse Recovery Time	I _S =9A, V _{GS} =0V diF/dt=100A/μs	-	575	-	nS
Q _{rr}	Reverse Recovery Charge		-	9.9	-	μC

- Notes : 1, L=20.8mH, I_{AS}=9A, V_{DD}=50V, R_G=25Ω, Starting T_J=25°C
 2, Repetitive Rating : Pulse width limited by maximum junction temperature
 3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%
 4, Essentially Independent of Operating Temperature

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

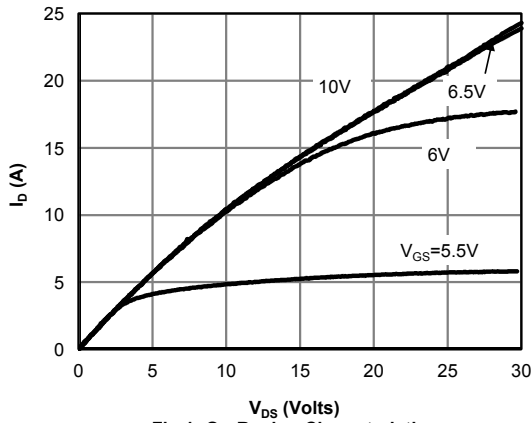


Fig 1: On-Region Characteristics

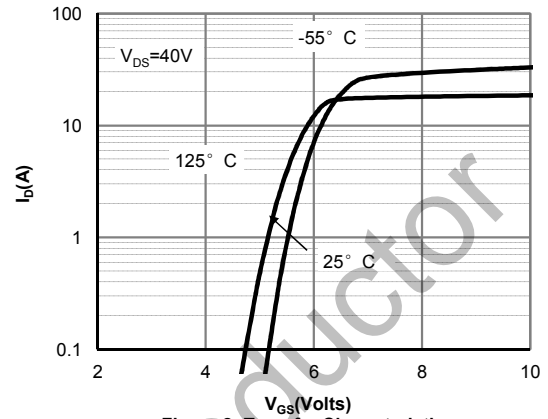


Figure 2: Transfer Characteristics

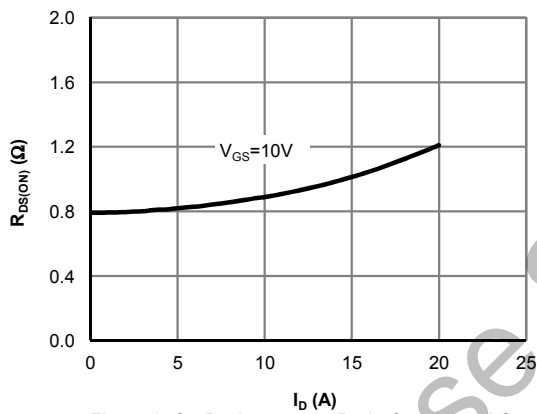


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

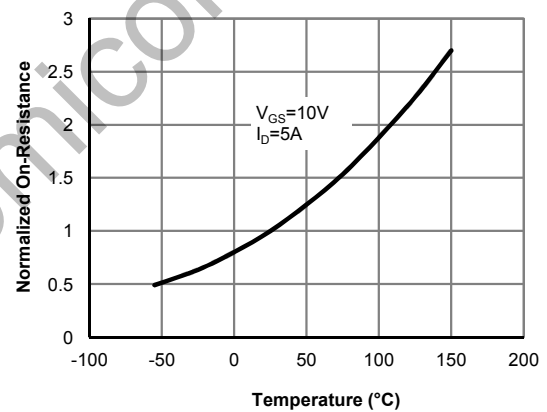


Figure 4: On-Resistance vs. Junction Temperature

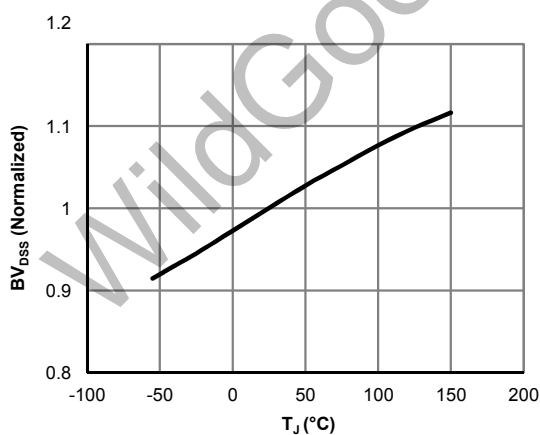


Figure 5: Break Down vs. Junction Temperature

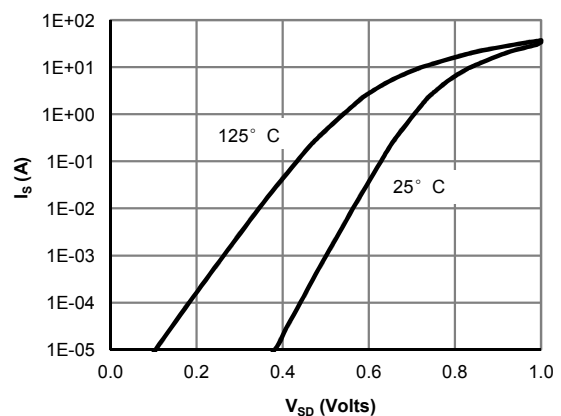


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

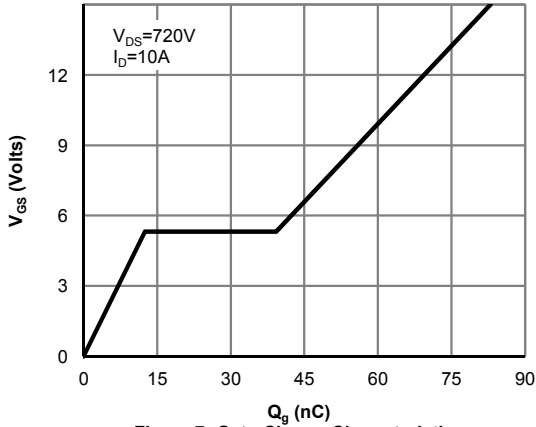


Figure 7: Gate-Charge Characteristics

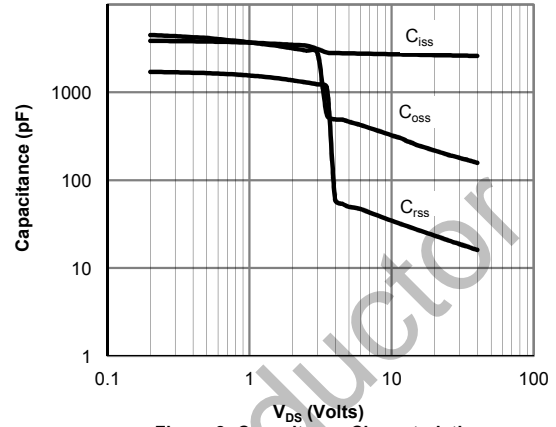


Figure 8: Capacitance Characteristics

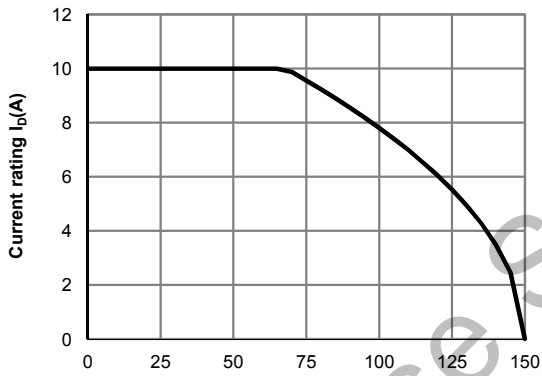


Figure 9: Current Derating (Note B)

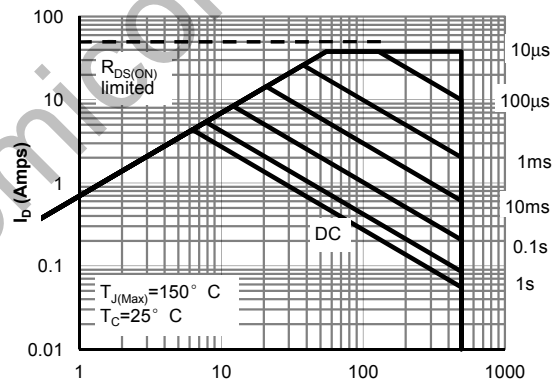


Figure 10: Maximum Forward Biased Safe Operating Area for AOTF10N90 (Note F)

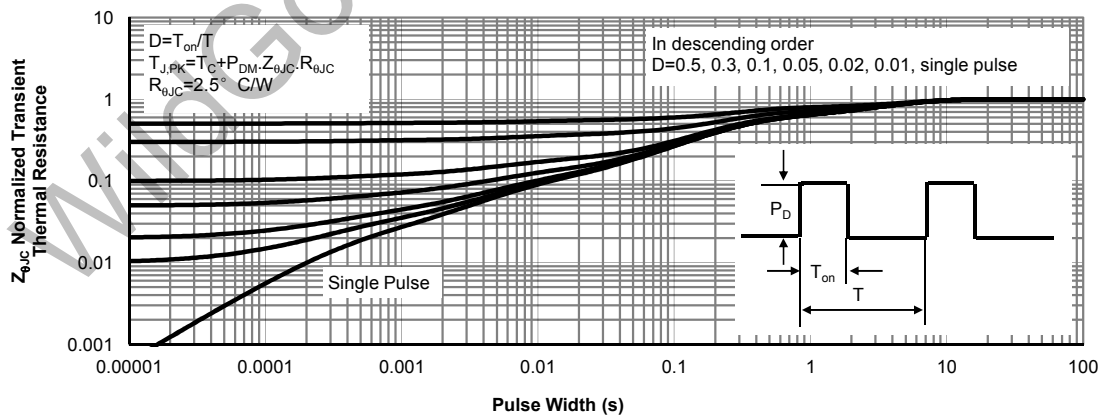
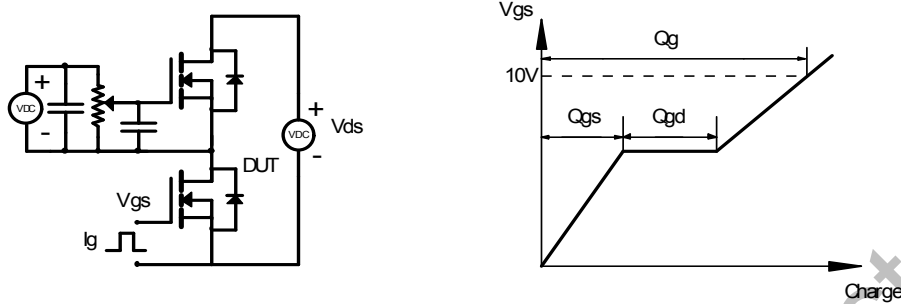
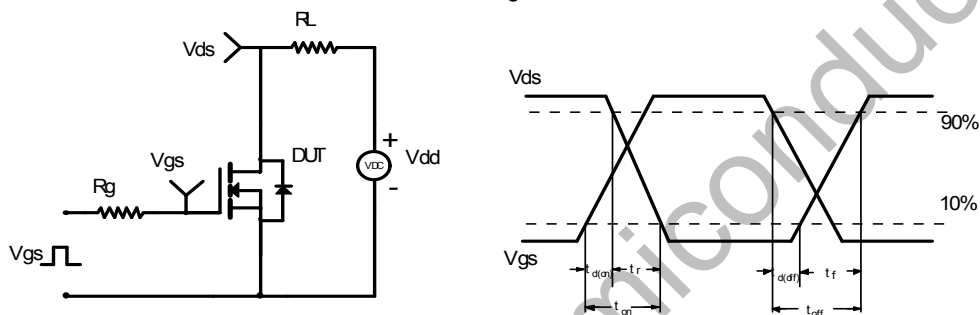


Figure 11: Normalized Maximum Transient Thermal Impedance for AOTF10N90 (Note F)

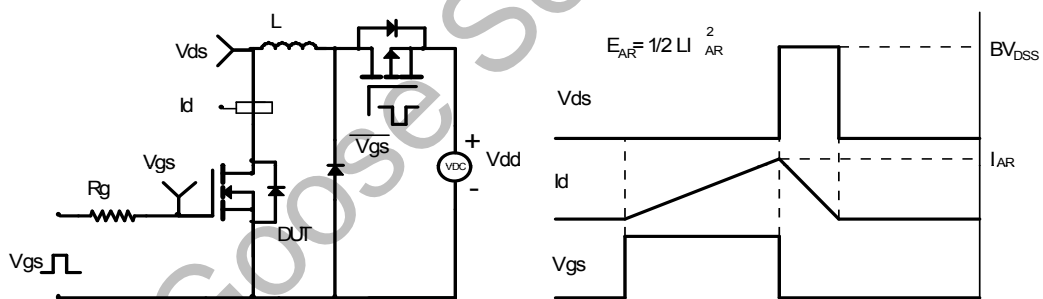
Gate Charge Test Circuit & Waveform



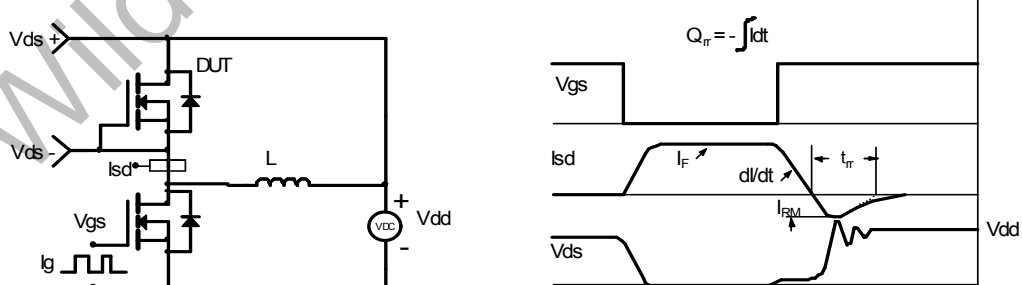
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



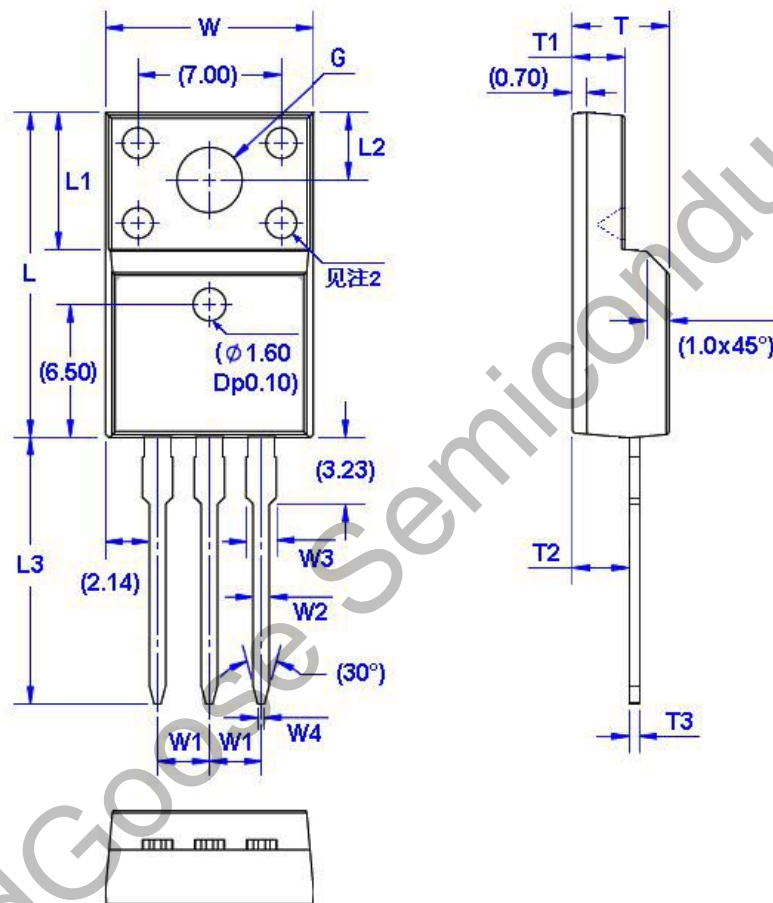
Diode Recovery Test Circuit & Waveforms



Package Dimension

TO-220F

Unit: mm



Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.96	10.36	W4	0.25	0.45	L3	12.78	13.18	T3	0.45	0.60
W1	2.54 (TYP)		L	15.67	16.07	T	4.50	4.90	G(Φ)	3.08	3.28
W2	0.70	0.90	L1	6.48	6.88	T1	2.34	2.74			
W3	1.24	1.47	L2	3.20	3.40	T2	2.56	2.96			

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